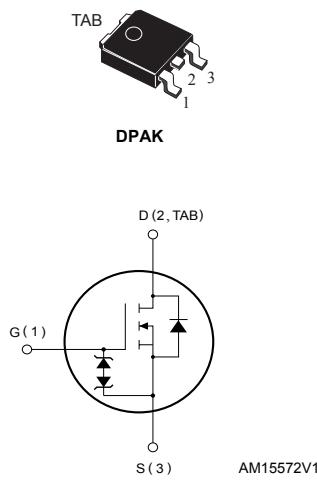


## N-channel 400 V, 0.59 Ω typ., 6 A MDmesh™ M2 Power MOSFET in a DPAK package

### Features



Order code	$V_{DS} @ T_{Jmax}$	$R_{DS(on)}\text{max.}$	$I_D$
STD9N40M2	450 V	0.8 Ω	6 A

- Extremely low gate charge
- Excellent output capacitance ( $C_{oss}$ ) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Product status	
STD9N40M2	
Product summary	
Order code	STD9N40M2
Marking	9N40M2
Package	DPAK
Packing	Tape and reel

## 1 Electrical ratings

**Table 1.** Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	400	V
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	6	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	3.8	A
$I_{DM}^{(1)}$	Drain current (pulsed)	24	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	60	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	V/ns
$T_j$	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
$T_{stg}$	Storage temperature range		

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 6 \text{ A}$ ,  $di/dt \leq 400 \text{ A}/\mu\text{s}$ ;  $V_{DS \text{ peak}} < V_{(BR)DSS}$ ,  $V_{DD} = 320 \text{ V}$ .
3.  $V_{DS} \leq 320 \text{ V}$ .

**Table 2.** Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	2.08	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	$^\circ\text{C}/\text{W}$

1. When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 3.** Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_{jmax}$ )	2.5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50 \text{ V}$ )	148	mJ

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	400			V
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, T_C = 125^\circ\text{C}$ <sup>(1)</sup>			100	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.59	0.8	$\Omega$

- Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	270	-	pF
$C_{oss}$	Output capacitance			22		
$C_{rss}$	Reverse transfer capacitance			0.7		
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ to } 320 \text{ V}$	-	94	-	pF
$R_g$	Gate input resistance	$f = 1 \text{ MHz}$ open drain	-	7.1	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 320 \text{ V}, I_D = 6 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	8.8	-	nC
$Q_{gs}$	Gate-source charge			1.7		
$Q_{gd}$	Gate-drain charge			4.8		

- $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 200 \text{ V}, I_D = 3 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	10.5	-	ns
$t_r$	Rise time			9		
$t_{d(off)}$	Turn-off delay time			7.5		
$t_f$	Fall time			21		

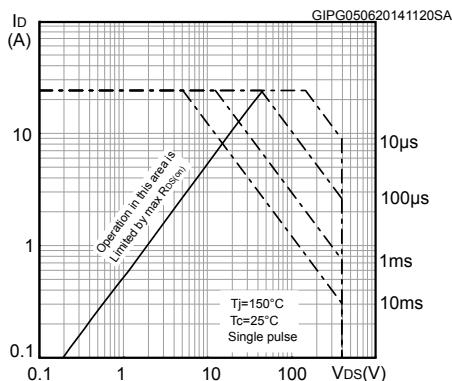
Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		6	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				24	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 6 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	208	ns	
$Q_{rr}$	Reverse recovery charge			1.2		
$I_{RRM}$	Reverse recovery current			11.5		
$t_{rr}$	Reverse recovery time	$I_{SD} = 6 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	264	ns	
$Q_{rr}$	Reverse recovery charge			1.6		
$I_{RRM}$	Reverse recovery current			12.5		

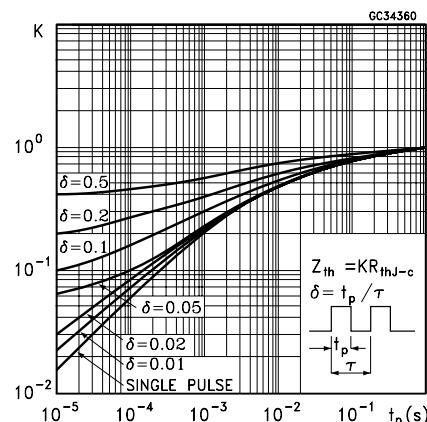
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics curves

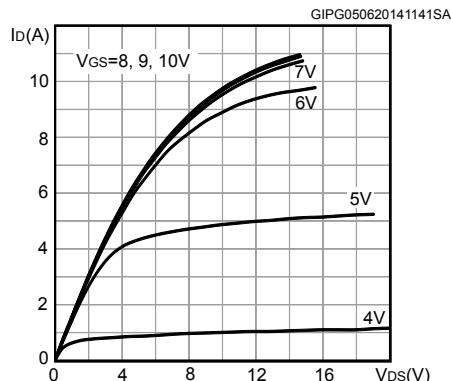
**Figure 1. Safe operating area**



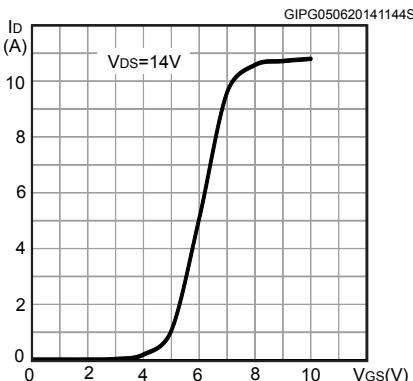
**Figure 2. Thermal impedance**



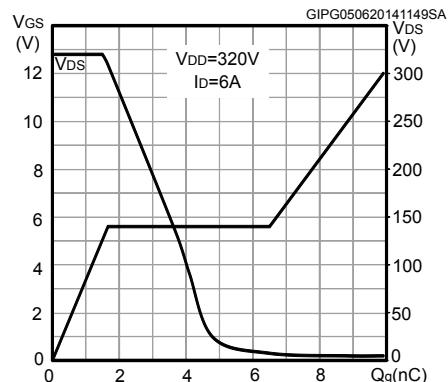
**Figure 3. Output characteristics**



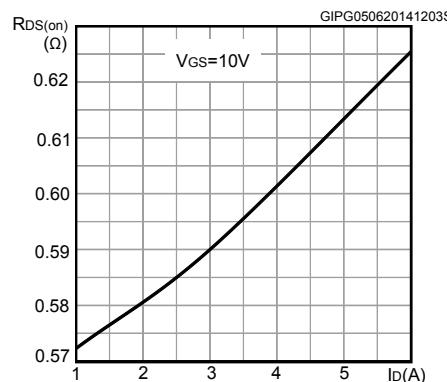
**Figure 4. Transfer characteristics**

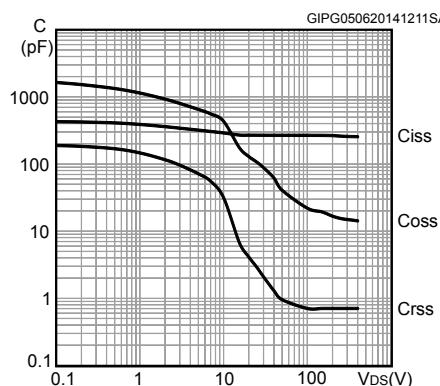
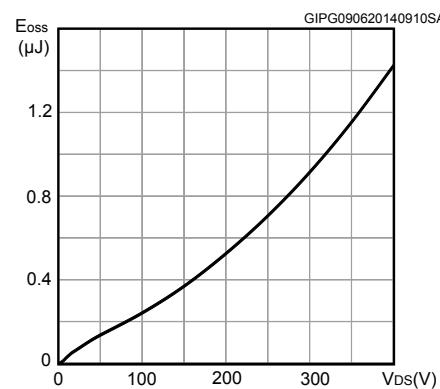
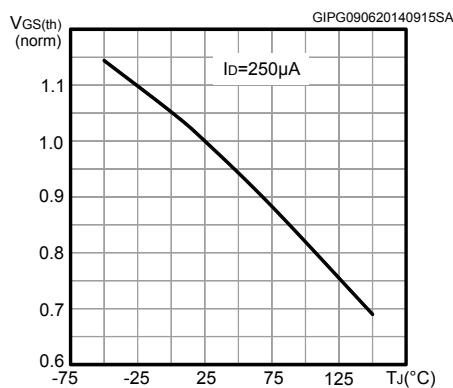
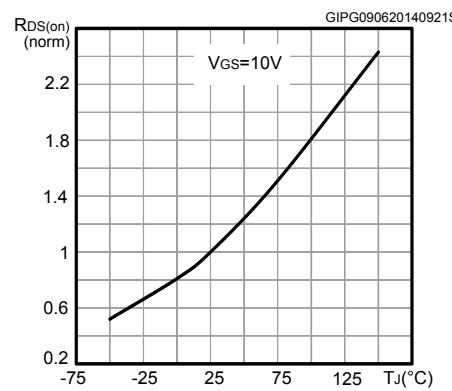
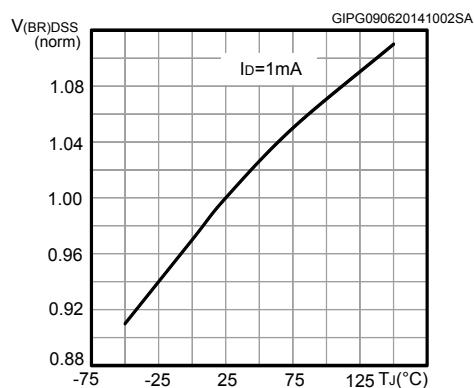
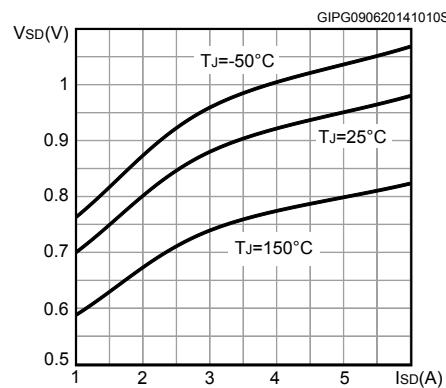


**Figure 5. Gate charge vs gate-source voltage**



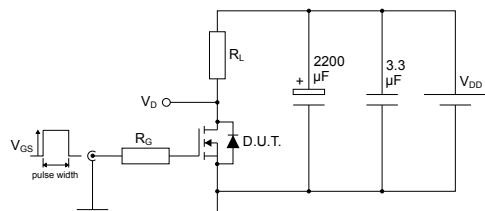
**Figure 6. Static drain-source on-resistance**



**Figure 7. Capacitance variations**

**Figure 8. Output capacitance stored energy**

**Figure 9. Normalized gate threshold voltage vs temperature**

**Figure 10. Normalized on-resistance vs temperature**

**Figure 11. Normalized V(BR)DSS vs temperature**

**Figure 12. Source-drain diode forward characteristics**


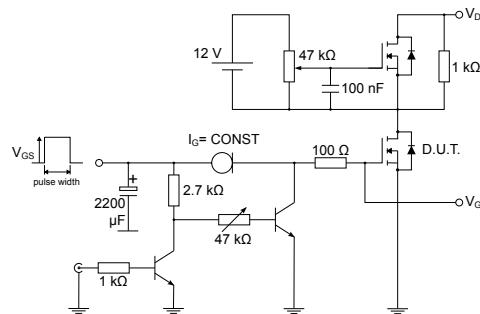
### 3 Test circuits

**Figure 13.** Test circuit for resistive load switching times



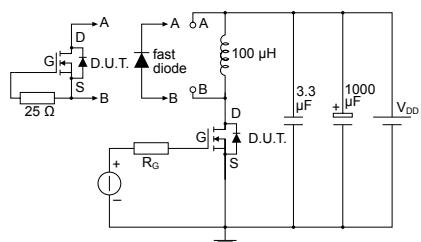
AM01468v1

**Figure 14.** Test circuit for gate charge behavior



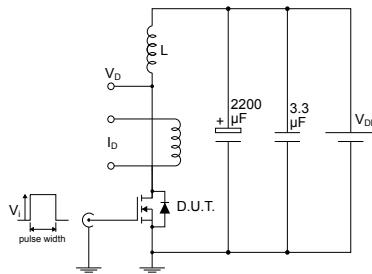
AM01469v1

**Figure 15.** Test circuit for inductive load switching and diode recovery times



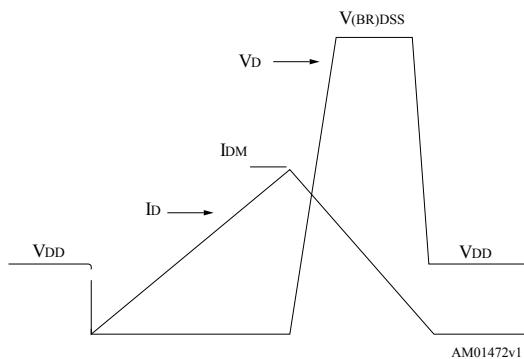
AM01470v1

**Figure 16.** Unclamped inductive load test circuit



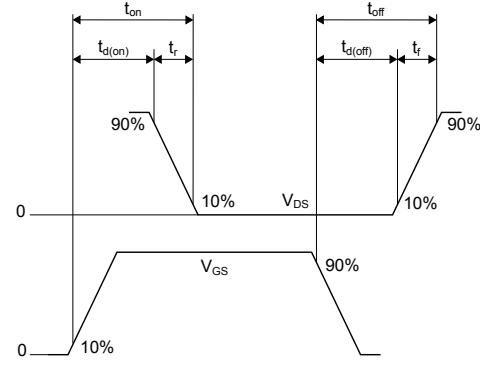
AM01471v1

**Figure 17.** Unclamped inductive waveform



AM01472v1

**Figure 18.** Switching time waveform



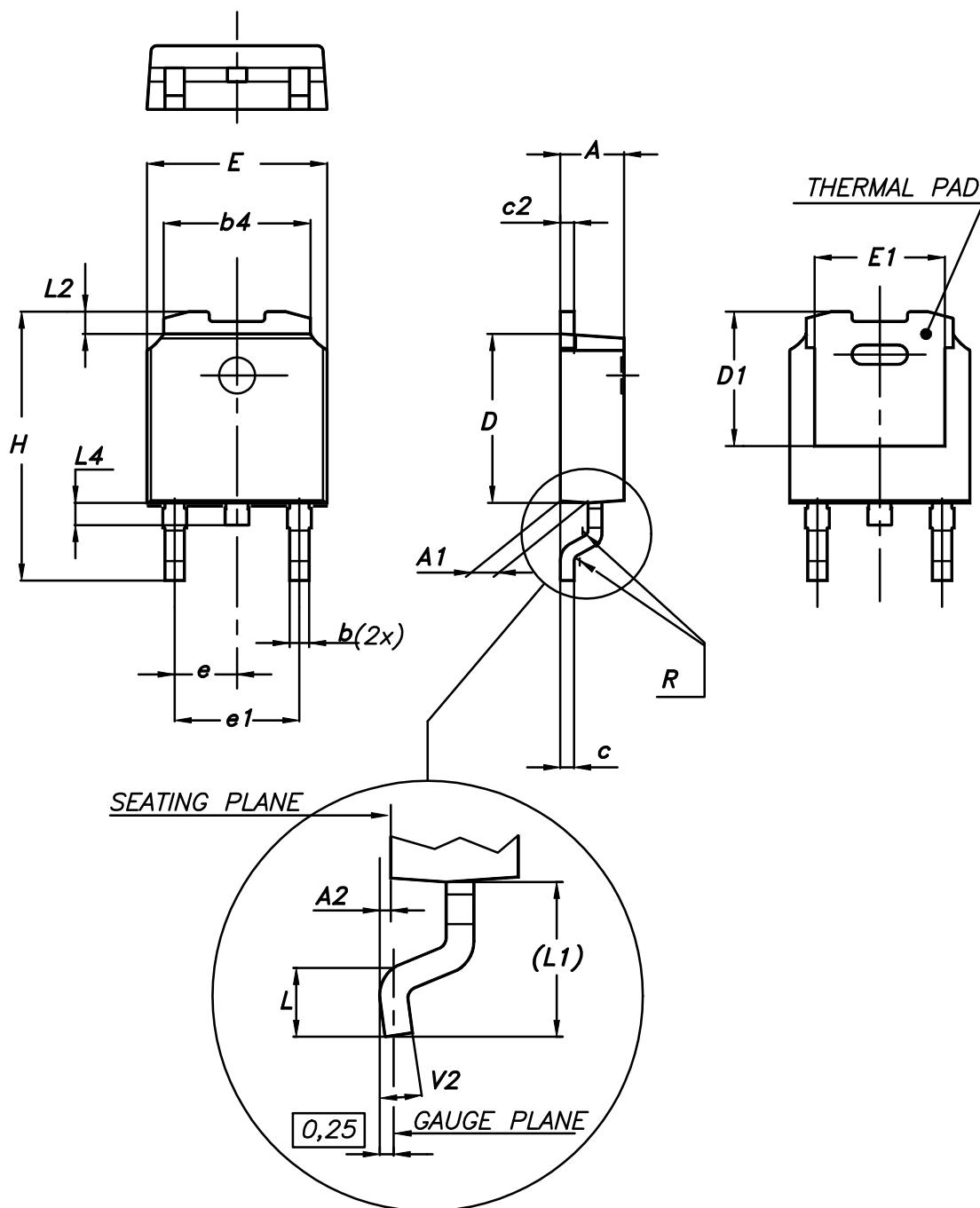
AM01473v1

**4****Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

#### 4.1 DPAK (TO-252) type A package information

Figure 19. DPAK (TO-252) type A package outline



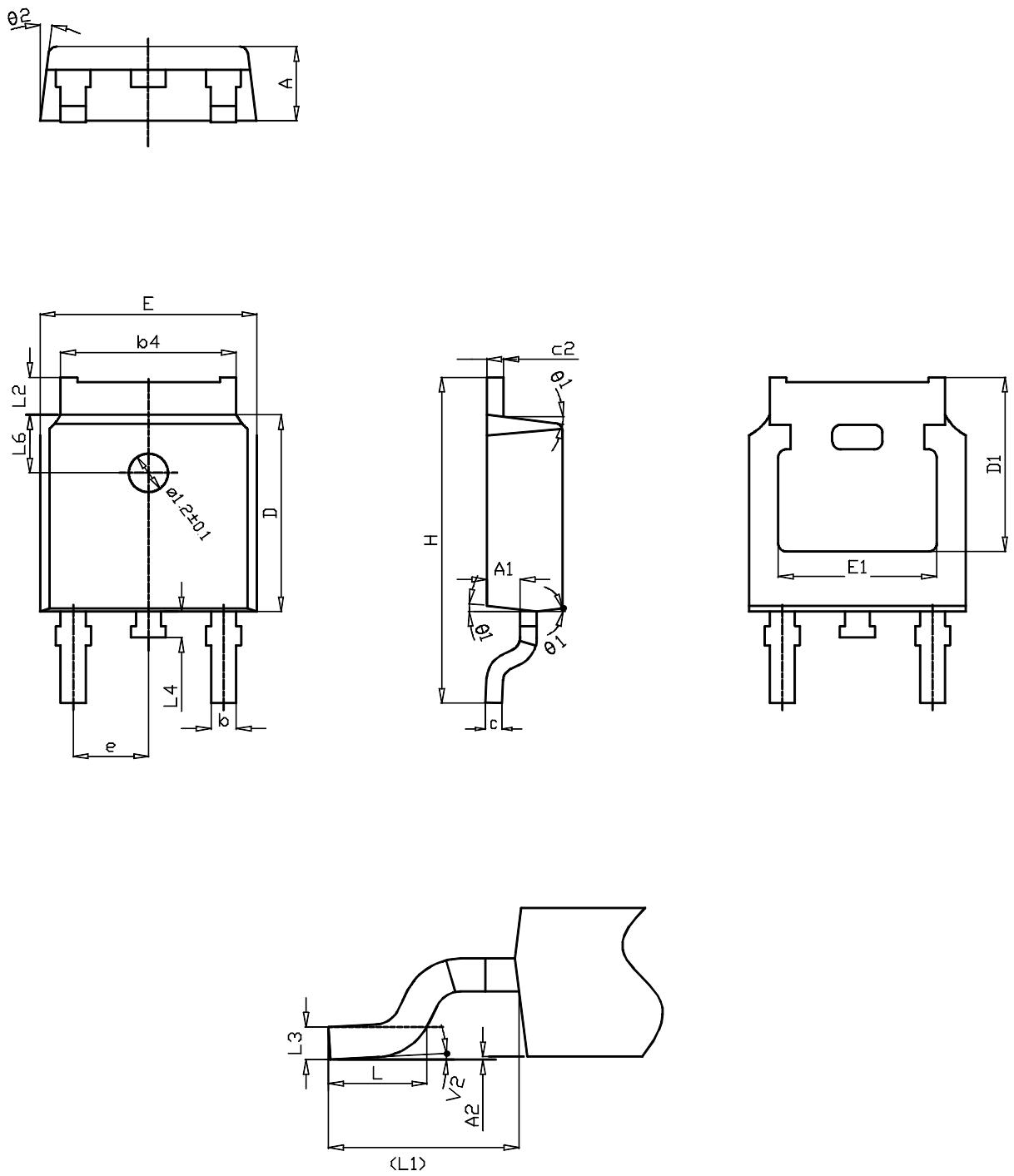
0068772\_A\_25

**Table 8. DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

## 4.2 DPAK (TO-252) type C package information

**Figure 20. DPAK (TO-252) type C package outline**

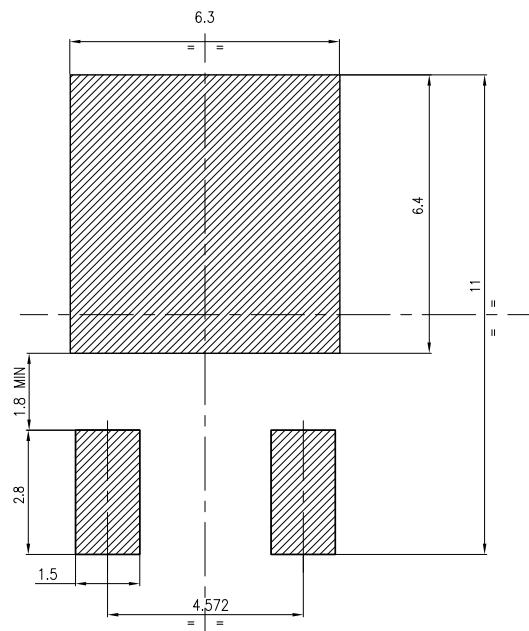


0068772\_C\_25

**Table 9. DPAK (TO-252) type C mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.25		
E	6.50	6.60	6.70
E1	4.70		
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

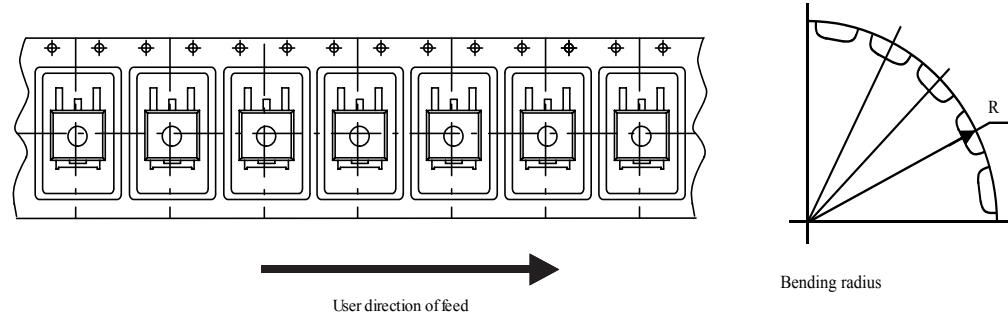
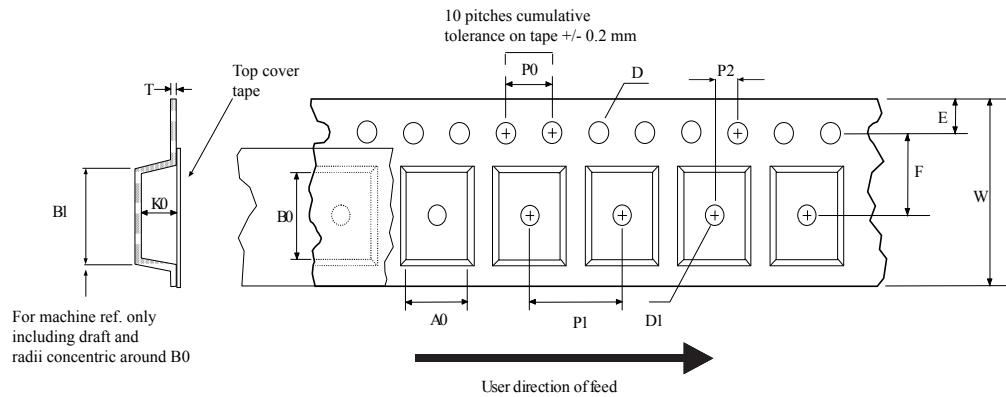
Figure 21. DPAK (TO-252) recommended footprint (dimensions are in mm)



FP\_0068772\_25\_C

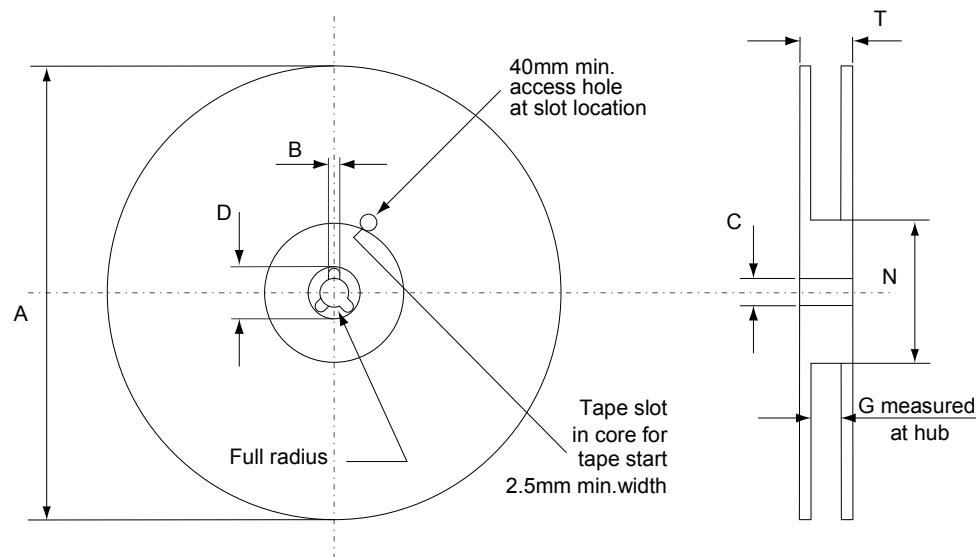
## 4.3 DPAK (TO-252) packing information

**Figure 22. DPAK (TO-252) tape outline**



AM08852v1

Figure 23. DPAK (TO-252) reel outline



AM06038v1

Table 10. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## Revision history

**Table 11. Document revision history**

Date	Version	Changes
09-Jan-2014	1	First release.
18-Jun-2014	2	<ul style="list-style-type: none"><li>– Modified: title</li><li>– Modified: values in <i>Table 4</i></li><li>– Modified: <math>R_{DS(on)}</math> and <math>I_{DSS}</math> (test conditions) in <i>Table 5</i></li><li>– Modified: the entire typical values in <i>Table 6, 7 and 8</i></li><li>– Added: <i>Table 8</i></li><li>– Added: <i>Section 2.1: Electrical characteristics (curves)</i></li><li>– Updated: <i>Section 4: Package mechanical data</i></li><li>– Minor text changes</li></ul>
20-Aug-2018	3	The document status is production data. Added <i>Section 4.2 DPAK (TO-252) type C package information</i> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings .....</b>	<b>2</b>
<b>2</b>	<b>Electrical characteristics.....</b>	<b>3</b>
<b>2.1</b>	Electrical characteristics curves .....	5
<b>3</b>	<b>Test circuits .....</b>	<b>7</b>
<b>4</b>	<b>Package information.....</b>	<b>8</b>
<b>4.1</b>	DPAK (TO-252) type A package information .....	8
<b>4.2</b>	DPAK (TO-252) type C package information .....	10
<b>4.3</b>	DPAK (TO-252) packing information.....	13
	<b>Revision history .....</b>	<b>16</b>

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved

# X-ON Electronics

Largest Supplier of Electrical and Electronic Components

***Click to view similar products for MOSFET category:***

***Click to view products by STMicroelectronics manufacturer:***

Other Similar products are found below :

[614233C](#) [648584F](#) [IRFD120](#) [JANTX2N5237](#) [FCA20N60\\_F109](#) [FDZ595PZ](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [TPCC8103,L1Q\(CM](#)  
[MIC4420CM-TR](#) [VN1206L](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [SSM6J414TU,LF\(T](#) [751625C](#) [BUK954R8-60E](#)  
[DMN3404LQ-7](#) [NTE6400](#) [SQJ402EP-T1-GE3](#) [2SK2614\(TE16L1,Q\)](#) [2N7002KW-FAI](#) [DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [ECH8691-](#)  
[TL-W](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE221](#) [NTE2384](#) [NTE2903](#) [NTE2941](#) [NTE2945](#) [NTE2946](#) [NTE2960](#)  
[NTE2967](#) [NTE2969](#) [NTE2976](#) [NTE455](#) [NTE6400A](#) [NTE2910](#) [NTE2916](#) [NTE2956](#) [NTE2911](#) [DMN2080UCB4-7](#) [TK10A80W,S4X\(S](#)  
[SSM6P69NU,LF](#) [DMP22D4UFO-7B](#)